

**CLAIM AMENDMENT:**

Please amend claim 4.

Claims 1-3 (canceled)

Claim 4 (currently amended): A lead frame for the semiconductor device from which surplus resin can be detached without leaving burrs, comprising  
a first region in which a semiconductor chip can be encapsulated with resin;  
and  
a second region, which is adapted to be placed at a runner of a mold, in which an opening is formed, the opening having one end, which extends to the first region, and another end opposite to the one end being rounded.

Claim 5 (previously presented): A lead frame as claimed in claim 4 wherein the opening includes a first part and a second part, the first part being rectangularly shaped and the second part being semicircularly shaped.

Claim 6 (previously presented): A lead frame as claimed in claim 5 wherein the sides facing to each other of the first part are parallel to sides of the lead frame.

Claim 7 (previously presented): A lead frame as claimed in claim 4 wherein the first part is used for passing resin material, and the second part is used for storing resin material.